

SN54LVT16952, SN74LVT16952

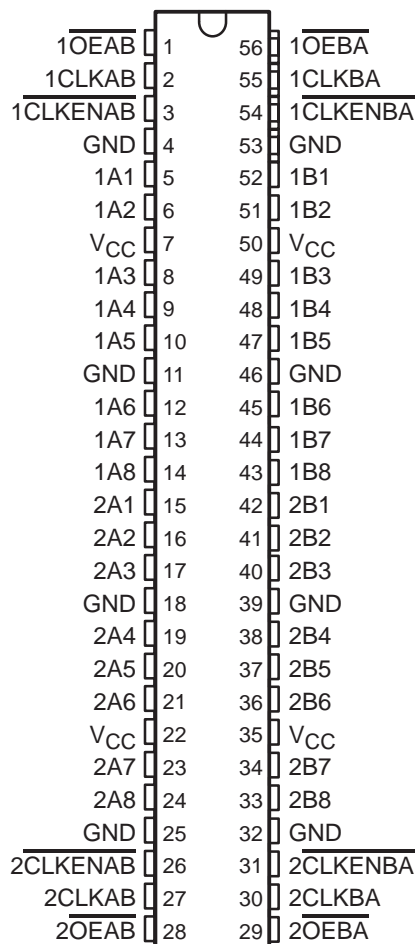
3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS

WITH 3-STATE OUTPUTS

SCBS151D – MAY 1992 – REVISED AUGUST 1996

- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- Members of the Texas Instruments *Widebus*™ Family
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Support Live Insertion
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54LVT16952 . . . WD PACKAGE
SN74LVT16952 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The 'LVT16952 are 16-bit registered transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable ($\overline{\text{CLKENAB}}$ or $\overline{\text{CLKENBA}}$) input is low. Taking the output-enable ($\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$) input low accesses the data on either port.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT16952 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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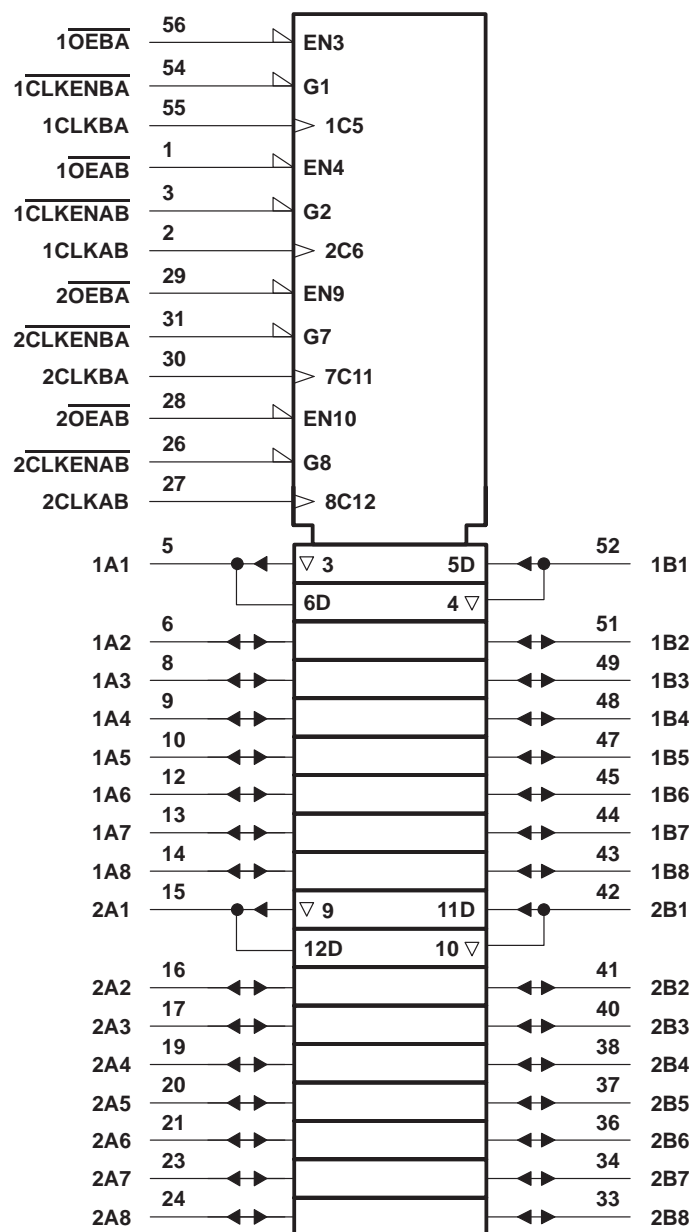
WITH 3-STATE OUTPUTS

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description (continued)

The SN54LVT16952 is characterized for operation over the full military temperature range of -55°C to 125°C .
The SN74LVT16952 is characterized for operation from -40°C to 85°C .

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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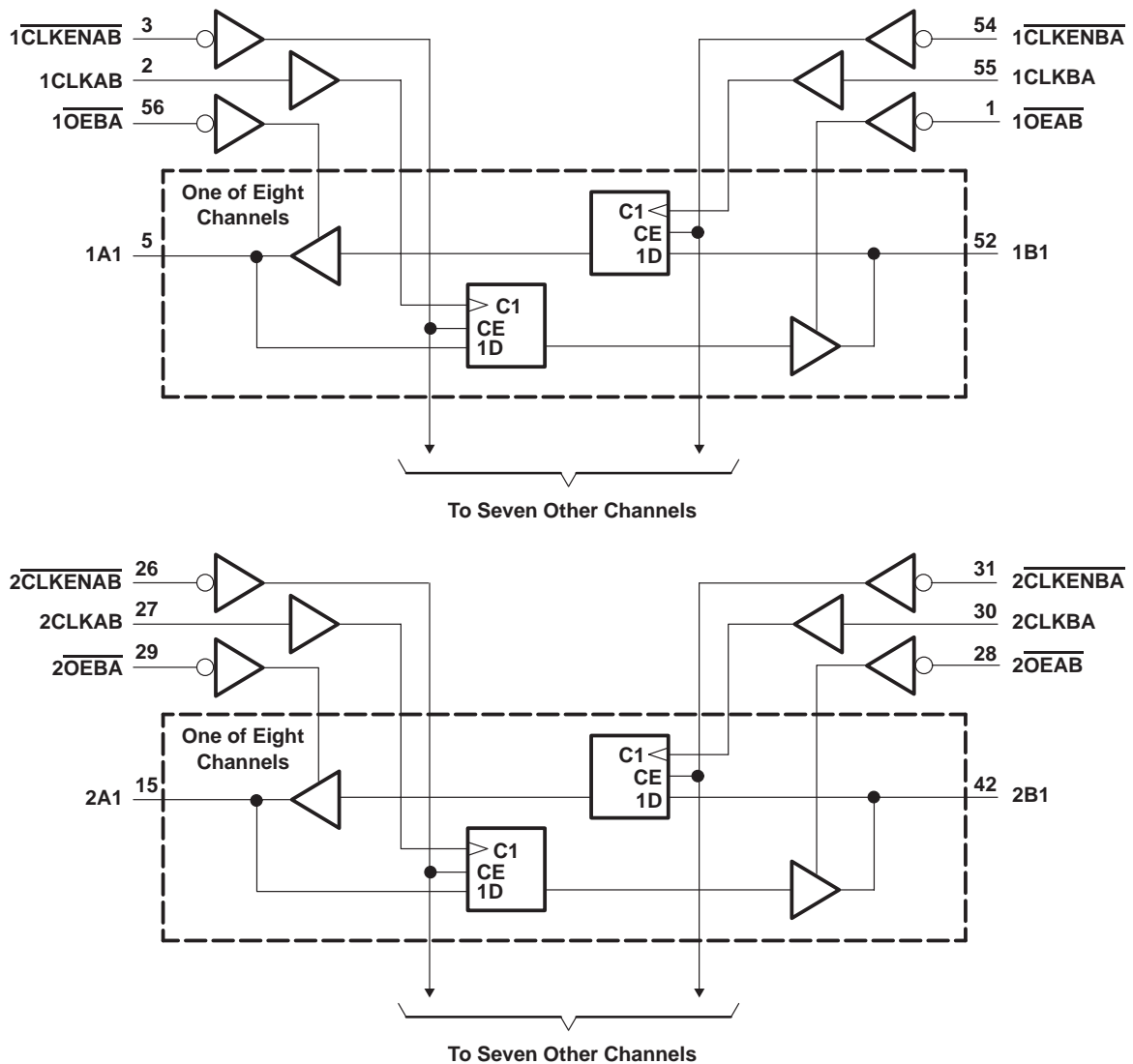
FUNCTION TABLE†

INPUTS				OUTPUT B
$\overline{\text{CLKENAB}}$	CLKAB	$\overline{\text{OEAB}}$	A	
H	X	L	X	B_0^\ddagger
X	L	L	X	B_0^\ddagger
L	\uparrow	L	L	L
L	\uparrow	L	H	H
X	X	H	X	Z

† A-to-B data flow is shown; B-to-A data flow is similar but uses $\overline{\text{CLKENBA}}$, CLKBA , and $\overline{\text{OEBA}}$.

‡ Level of B before the indicated steady-state input conditions were established

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Current into any output in the low state, I_O : SN54LVT16952	96 mA
SN74LVT16952	128 mA
Current into any output in the high state, I_O (see Note 2): SN54LVT16952	48 mA
SN74LVT16952	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

recommended operating conditions (see Note 4)

		SN54LVT16952		SN74LVT16952		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage		5.5		5.5	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54LVT16952			SN74LVT16952			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	$V_{CC} = 2.7\text{ V}$, $I_I = -18\text{ mA}$				-1.2			-1.2	V
V_{OH}	$V_{CC} = \text{MIN to MAX}^\ddagger$, $I_{OH} = -100\text{ }\mu\text{A}$		$V_{CC}-0.2$			$V_{CC}-0.2$			V
	$V_{CC} = 2.7\text{ V}$, $I_{OH} = -8\text{ mA}$		2.4			2.4			
	$V_{CC} = 3\text{ V}$	$I_{OH} = -24\text{ mA}$	2						
		$I_{OH} = -32\text{ mA}$				2			
V_{OL}	$V_{CC} = 2.7\text{ V}$	$I_{OL} = 100\text{ }\mu\text{A}$			0.2			0.2	V
		$I_{OL} = 24\text{ mA}$			0.5			0.5	
	$V_{CC} = 3\text{ V}$	$I_{OL} = 16\text{ mA}$			0.4			0.4	
		$I_{OL} = 32\text{ mA}$			0.5			0.5	
		$I_{OL} = 48\text{ mA}$			0.55				
		$I_{OL} = 64\text{ mA}$						0.55	
I_I	$V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ or GND	Control inputs			± 1			± 1	μA
	$V_{CC} = 0$ or MAX^\ddagger , $V_I = 5.5\text{ V}$				10			10	
	$V_{CC} = 3.6\text{ V}$	$V_I = 5.5\text{ V}$			100			20	
		$V_I = V_{CC}$			1			1	
		$V_I = 0$			-5			-5	
I_{off}	$V_{CC} = 0$, V_I or $V_O = 0$ to 4.5 V							± 100	μA
$I_{I(\text{hold})}$	$V_{CC} = 3\text{ V}$	$V_I = 0.8\text{ V}$			75			75	μA
		$V_I = 2\text{ V}$			-75			-75	
I_{OZH}	$V_{CC} = 3.6\text{ V}$, $V_O = 3\text{ V}$				1			1	μA
I_{OZL}	$V_{CC} = 3.6\text{ V}$, $V_O = 0.5\text{ V}$				-1			-1	μA
I_{CC}	$V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ or GND $I_O = 0$,	Outputs high			0.12			0.12	mA
		Outputs low			5			5	
		Outputs disabled			0.12			0.12	
ΔI_{CC}^\S	$V_{CC} = 3\text{ V to } 3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at V_{CC} or GND				0.2			0.2	mA
C_i	$V_I = 3\text{ V or } 0$				4			4	pF
C_{io}	$V_O = 3\text{ V or } 0$				13			13	pF

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

§ Unused pins at V_{CC} or GND¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			SN54LVT16952				SN74LVT16952				UNIT
			$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		0	150	0	150	0	150	0	150	MHz
t _w	Pulse duration	CLKEN high	3.3		3.3		3.3		3.3		ns
		CLK high or low	3.3		3.3		3.3		3.3		
t _{su}	Setup time	A or B before CLK	2.6		3.3		2.1		2.9		ns
		CLKEN before CLK	1.2		1.6		1.2		1.6		
t _h	Hold time	A or B after CLK	0.7		0.7		0.7		0.7		ns
		CLKEN after CLK	1.4		1.5		1.4		1.5		

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVT16952				SN74LVT16952				UNIT	
			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V			
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
f _{max}			150		150		150		150		MHz	
t _{PLH}	CLKBA or CLKAB	A or B	1.6	5.7	7.4		2	3.4	5.8	7.1		ns
t _{PHL}			2	6	7		2	3.4	5.8	6.9		
t _{PZH}	OEBA̅ or OEAB	A or B	1	5	7.3		1	2.7	5.6	6.7		ns
t _{PZL}			1.2	5.2	5.9		1.2	2.7	6.5	8		
t _{PHZ}	OEBA̅ or OEAB	A or B	1.8	6.7	7.3		2.3	3.9	6.3	6.9		ns
t _{PLZ}			1.2	5.8	6		2.2	3.9	5.1	5.3		

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

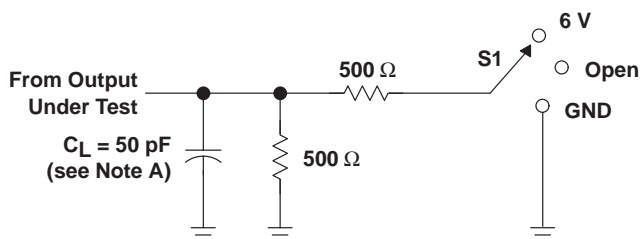
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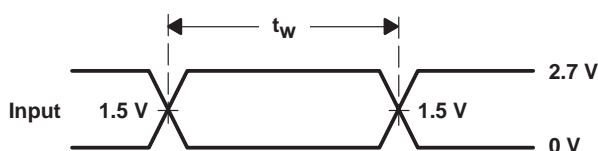
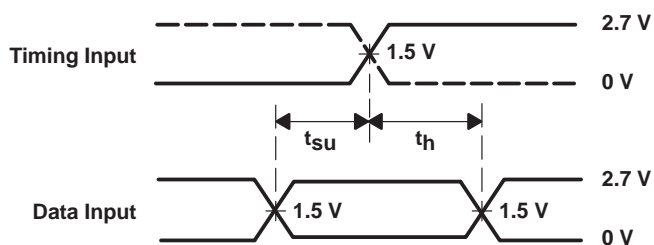
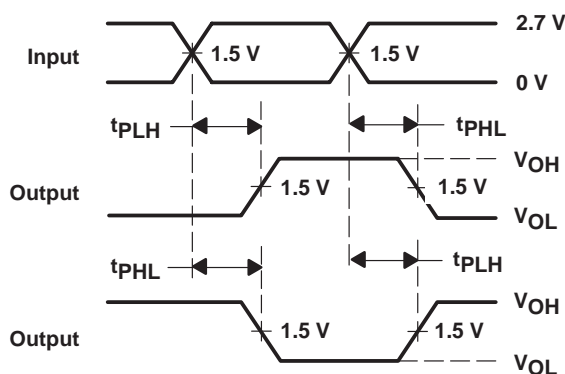
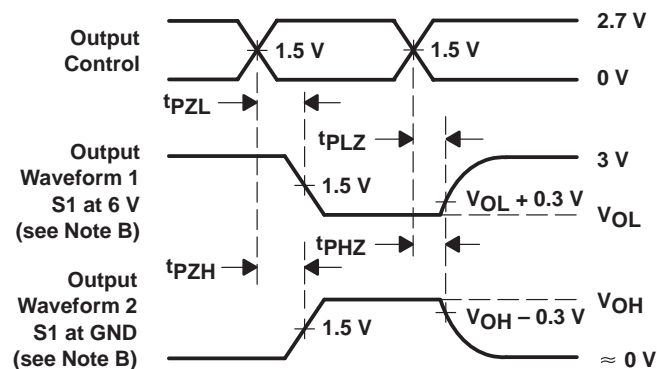
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PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

VOLTAGE WAVEFORMS
PULSE DURATIONVOLTAGE WAVEFORMS
SETUP AND HOLD TIMESVOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTSVOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVT16952DGGR	NRND	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16952	
SN74LVT16952DL	NRND	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT16952	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT16952DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

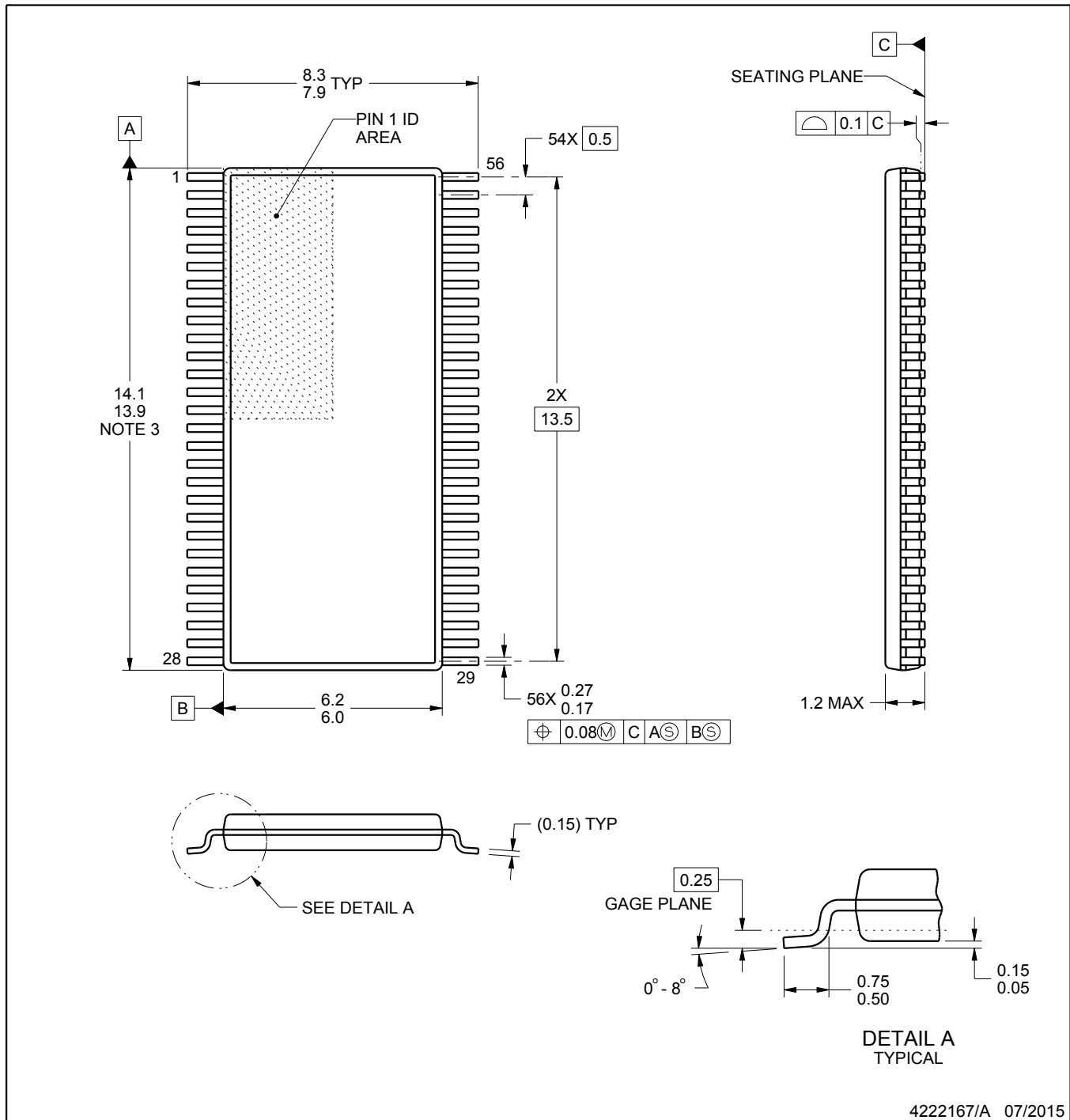
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT16952DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118



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NOTES:

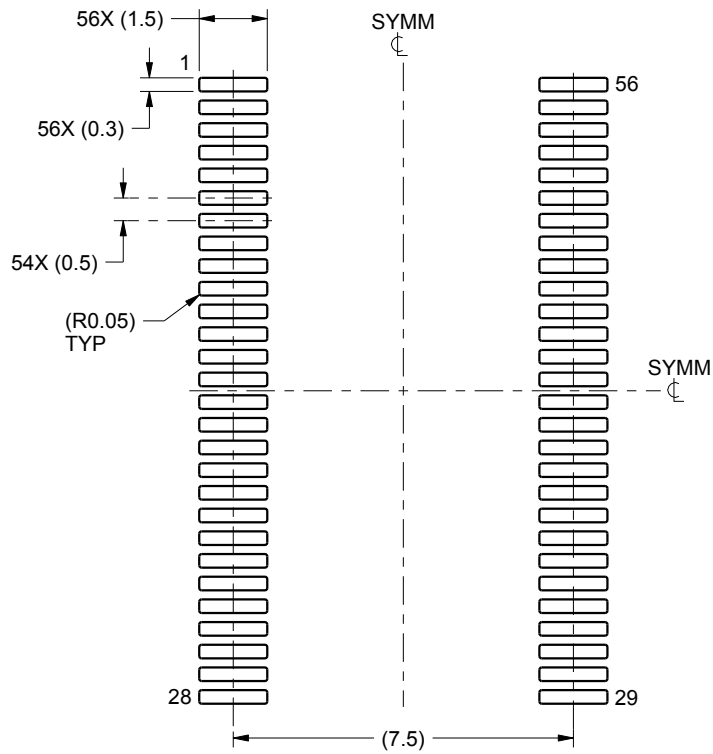
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

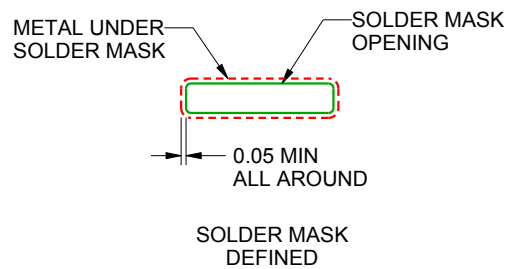
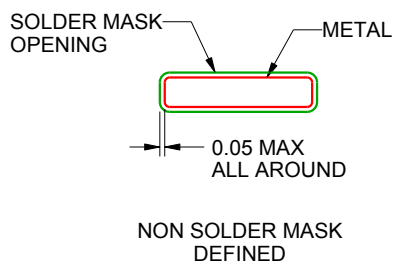
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

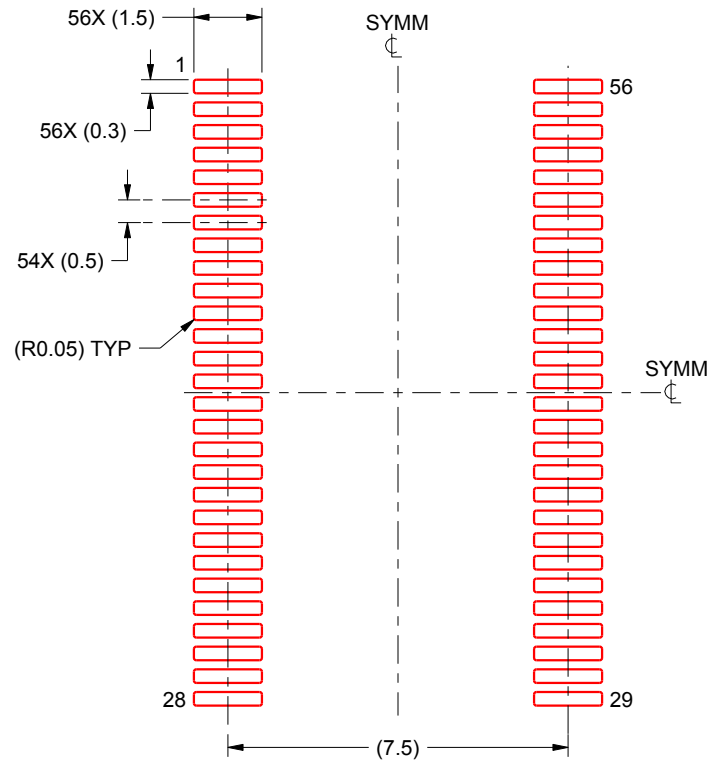
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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